



Ref	Min	Nominal	Max
A	1.19	1.27	1.35
A1	0.22	0.27	0.32
b	0.31	0.36	0.41
D	10.00 BSC		
E	10.00 BSC		
D1	5.25 BSC		
E1	3.75 BSC		
DE	0.375 BSC		
SE	0.375 BSC		
e	0.75 BSC		

Ref	Tolerance of, from and position
aaa	0.10
bbb	0.10
ddd	0.10
eee	0.15
fff	0.08

1. Dimensions in Millimeters.
2. The 'e' represents the basic solder ball grid pitch.
- ③ 'b' is measurable at the maximum solder ball diameter in a plane parallel to datum C.
- ④ Dimension 'ddd' is measured parallel to primary datum C.
- ⑤ Primary datum C (seating plane) is defined by the crowns of the solder balls.
6. Package dimensions refer to JEDEC MO-205 Rev. G.

